Peeling and Stripping Tool for HV Cables
Models CP90 and CP130

Application

This is a cost efficient tool for preparing cables in the field, before mounting joints and terminations. The same tool can be used for peeling the semicon and for stripping the main insulation.

CP90 and CP130 may also be used in combination with our optional driving unit, Model CPD90-130. This method is efficient when relatively long ends for terminations have to be prepared.

Peeling of Bonded Semicon

The peeling depth can easily be adjusted with the fine adjustment screw.

As the peeling knife is firmly fixed to one of the rollers running on the surface of the cable, the knife follows exactly the contour of the cable, even if it is not completely round.

The feed for the peeling process is built into the guiding rollers.

The special shape of the knife provides a very smooth surface on the insulation. The transition between insulation and semicon has an angle of some 6-10 °. This provides a perfect fit for slip-on terminations and joints. As a general rule, rework with polishing sand paper or similar means is not needed.

Main Benefits

- One tool, two operations: Peeling and insulation stripping
- Equipped with guiding rollers, no greasing of cable surface needed
- Very smooth insulation surface, no regrinding needed
- Smooth transition between insulation and semicon, typically no rework is needed
- Wide range of cable diameters
- Easy ergonomic handling
- Handles slightly bent cables without problems
- Driving unit attachable
Scope of Supply

- 1 Toolbox
- 1 Base tool with knives for peeling and stripping
- 1 Instruction manual English
- 1 Spare knife for peeling - FK-CP
- 1 Spare knife for stripping insulation - IK-CP

Options

- 1 Set of 3 spare knives for peeling - FK-CP
- 1 Set of 3 spare knives for stripping - IK-CP
- 1 Driving Unit - CPD90-130

Main Technical Data

<table>
<thead>
<tr>
<th></th>
<th>CP90</th>
<th>CP130</th>
</tr>
</thead>
<tbody>
<tr>
<td>Range of cable diameter D</td>
<td>mm</td>
<td>40..90</td>
</tr>
<tr>
<td>Weight of tool</td>
<td>kg</td>
<td>4.0</td>
</tr>
<tr>
<td>Maximum peeling depth</td>
<td>mm</td>
<td>2.0</td>
</tr>
<tr>
<td>Min. length of remaining semicon R</td>
<td>mm</td>
<td>~70</td>
</tr>
<tr>
<td>Cutting depth for insulation C</td>
<td>mm</td>
<td>3...35</td>
</tr>
<tr>
<td>Gross weight</td>
<td>kg</td>
<td>8.0</td>
</tr>
<tr>
<td>Dimensions of outer carton box WxLxH</td>
<td>cm</td>
<td>44x51x20</td>
</tr>
</tbody>
</table>

Stripping of Insulation

The cutting depth C can easily be adjusted to the thickness of the insulation.

The insulation stripping knife arrangement is such that the thickness of the shaving is always constant. This allows to operate the tool with constant force.

The same knife is suitable for cutting a stepped insulation.

Chamfering of Insulation

For chamfering the same knife is used as for peeling of the semicon. The chamfer angle will be about 20 degrees to the cable axis.